

IN THE CLAIMS:

Amendments to the claims:

This listing of claims will replace all prior versions, and listings of claims in the application.

Listing of claims:

21. (Original) An EMI/RFI shielding device comprising:  
a shaped polymer substrate comprised of a recycled metallized polymer substrate, wherein the shaped polymer substrate is substantially conductive; and  
a conductive material on at least one surface of the shaped polymer substrate.
22. (Original) The EMI/RFI shielding device of claim 21 wherein the recycled metallized polymer substrate comprises a reground and re-extruded metallized thermoform.
23. (Currently amended) The EMI/RFI shielding device of claim 21 wherein the ~~metallized thermoform~~ shaped polymer substrate comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol.
24. (Original) The EMI/RFI shielding device of claim 21 wherein the conductive material has a thickness between 1.0 micron and 50.0 microns.
25. (Original) The EMI/RFI shielding device of claim 21 wherein the conductive material comprises aluminum.
26. (Original) The EMI/RFI shielding device of claim 21 wherein the conductive material comprises a substantially uniform thickness over at least one surface of the shaped polymer substrate.

27. (Original) The EMI/RFI shielding device of claim 21 wherein the shaped polymer substrate has a thickness between 0.006 inches to 0.100 inches.

28. (Original) The EMI/RFI shielding device of claim 21 wherein the shaped polymer substrate comprises:

a first surface;

a plurality of sidewalls that comprise a first end and a second end, wherein a first end of each of the sidewalls are coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion; and

a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion.

29. (Original) An EMI/RFI shield comprising:

a thermoformed thin-walled shape formed of a recycled metallized polymeric material, wherein the thermoformed thin-walled shape comprises an inner surface, an outer surface and edges; and

a conductive material deposited on at least one of the inner surface and outer surface, wherein the conductive coating comprises a substantially even thickness between 1 micron to 50 microns.

30. (Original) The EMI/RFI shield of claim 29 wherein the conductive material comprises vacuum deposited aluminum.

31. (Original) The EMI/RFI shield of claim 29 wherein the recycled metallized polymeric material comprises a reground and re-extruded metal layer and a polymeric material.

32. (Original) The EMI/RFI shield of claim 29 wherein the polymeric material comprises polyvinyl chloride, polycarbonate, polybutylene terephthalate, or polyethylene terephthalate glycol.

33. (Original) The EMI/RFI shield of claim 29 wherein the thermoformed thin-walled shape has a thickness between 0.006 inches to 0.100 inches.

34. (Original) The EMI/RFI shield of claim 29 wherein the thermoformed thin-walled shape comprises:

a first surface;

a plurality of sidewalls that comprise a first end and a second end, wherein a first end is coupled to the first surface, wherein the sidewalls extend at an angle from the first surface, wherein the first surface and sidewalls define an enclosure portion; and

a peripheral flange coupled to the second end of the sidewalls that extends around the enclosure portion.

35. to 45. (Canceled)

46. The EMI/RFI shielding device of claim 21 further comprising grinding and re-extruding a metal material along with the polymer substrate.

47-48. (Canceled)

49. (New) The EMI/RFI shielding device of claim 21 wherein the conductive material comprises copper.

50. (New) The EMI/RFI shielding device of claim 21 wherein the conductive material comprises nickel.

51. (New) The EMI/RFI shield of claim 29 wherein the conductive material comprises vacuum deposited copper.

52. (New) The EMI/RFI shield of claim 29 wherein the conductive material comprises vacuum deposited nickel.